BYC10-600CT

FEATURES

- Dual diode
- Extremely fast switching
- Low reverse recovery current
- Low thermal resistance

Reduces switching losses in associated MOSFET

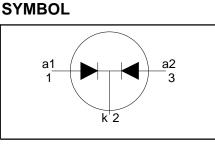
APPLICATIONS

Active power factor correction

Half-bridge lighting ballasts

• Half-bridge/ full-bridge switched mode power supplies.

The BYC10-600CT is supplied in the SOT78 (TO220AB) conventional leaded package.



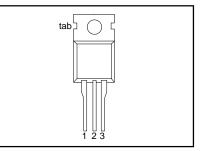
PINNING

PIN	DESCRIPTION	
1	anode 1	
2	cathode	
3	anode 2	
tab	cathode	

QUICK REFERENCE DATA

$V_{R} = 600 V$ $V_{F} \le 1.75 V$ $I_{O(AV)} = 10 A$ $t_{rr} = 19 ns (typ)$

SOT78 (TO220AB)



LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{RRM}	Peak repetitive reverse voltage		-	600	V
V _{RWM}	Crest working reverse voltage		-	600	V
V _R	Continuous reverse voltage	T _{mb} ≤ 110 °C	-	500	V
I _{O(AV)}	Average output current (both diodes conducting)	$\delta = 0.5$; with reapplied V _{RRM(max)} ; T _{mb} $\leq 50 \degree C^1$	-	10	A
I _{FRM}	Repetitive peak forward current per diode	δ = 0.5; with reapplied V _{RRM(max)} ; T _{mb} $\leq 50 °C^1$	-	10	A
I _{FSM}	Non-repetitive peak forward	t = 10 ms	-	40	A
	current per diode	t = 8.3 ms sinusoidal; $T_j = 150^{\circ}C$ prior to surge with reapplied $V_{RWM(max)}$	-	44	A
T _{stg}	Storage temperature	(max)	-40	150	j.Č
l I _j	Operating junction temperature		-	150	°C

THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
R _{th j-mb} R _{th j-a}	Thermal resistance junction to mounting base Thermal resistance junction to ambient	per diode both diodes in free air.		- - 60	2.5 2.2 -	K/W K/W K/W

¹ $T_{mb(max)}$ limited by thermal runaway

ELECTRICAL CHARACTERISTICS

 $T_i = 25$ °C, per diode unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V _F	Forward voltage	$I_{\rm F} = 5 \text{ A}; T_{\rm L} = 150^{\circ} \text{C}$	-	1.4	1.75	V
		$I_{\rm F} = 10 \text{ Å}; T_{\rm j} = 150^{\circ}\text{C}$	-	1.75	2.2	V
I _R	Reverse current	$I_{F} = 5 \text{ A};$ $V_{R} = 600 \text{ V}$	-	2.0	2.9 100	V μA
'R		$V_{R}^{R} = 500 V; T_{j} = 100 °C$	-	0.9	3.0	mΑ
t _{rr}	Reverse recovery time	$I_F = 1 \text{ A}; V_R = 30 \text{ V}; dI_F/dt = 50 \text{ A}/\mu\text{s}$	-	30	50	ns
t _{rr}	Reverse recovery time	$I_{\rm F} = 5 \text{ A}; V_{\rm R} = 400 \text{ V};$	-	19	-	ns
t _{rr}	Reverse recovery time	$dI_F/dt = 500 A/\mu s$ $I_F = 5 A; V_R = 400 V;$ $dI_F/dt = 500 A/\mu s; T_j = 100°C$	-	25	30	ns
I _{rrm}	Peak reverse recovery current	$I_{\rm F} = 5 \text{ A}; V_{\rm R} = 400 \text{ V};$	-	0.7	3	А
I _{rrm}	Peak reverse recovery current	$dI_F/dt = 50^{\circ}A/\mu s; T_i = 125^{\circ}C$ $I_F = 5 A; V_R = 400 V;$ $dI_F/dt = 500^{\circ}A/\mu s; T_j = 125^{\circ}C$	-	8	11	A
V _{fr}	Forward recovery voltage	$I_F = 10 \text{ A}; \text{ d}I_F/\text{d}t = 100 \text{ A}/\mu\text{s}$	-	9	11	V

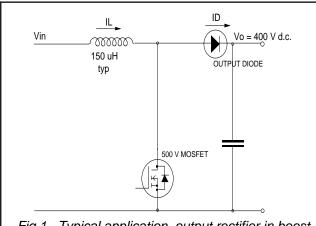
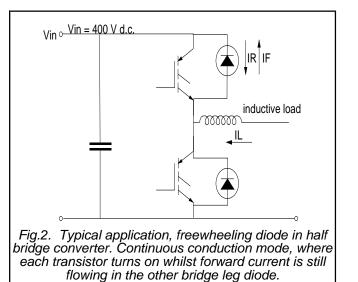
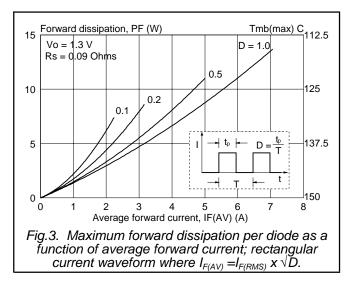


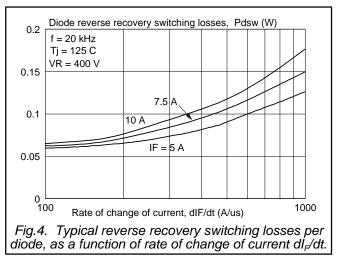
Fig.1. Typical application, output rectifier in boost converter power factor correction circuit. Continuous conduction mode, where the transistor turns on whilst forward current is still flowing in the diode.

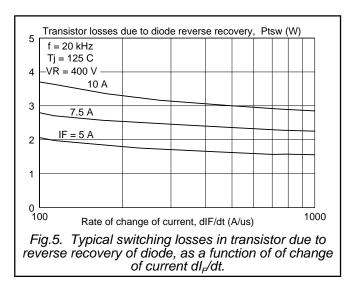


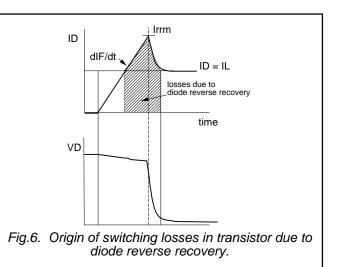
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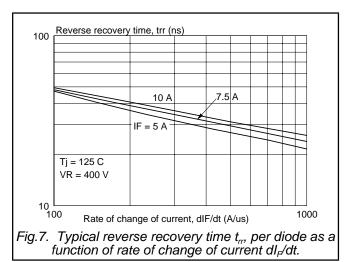
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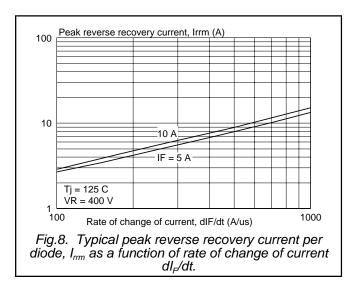




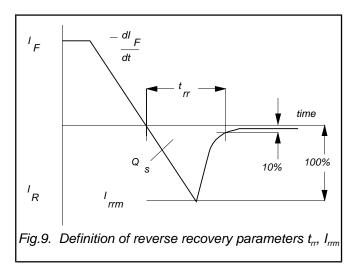


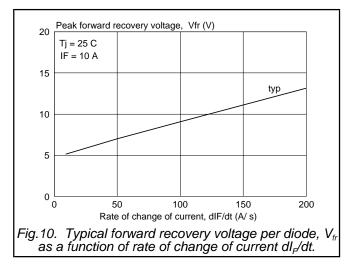


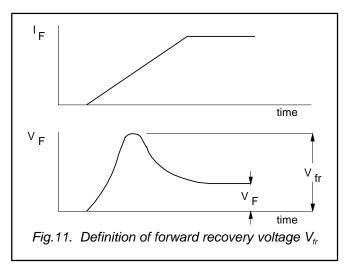


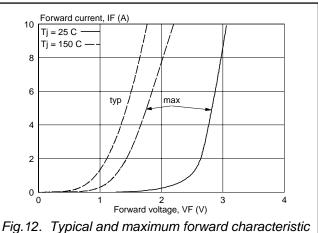


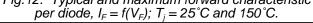
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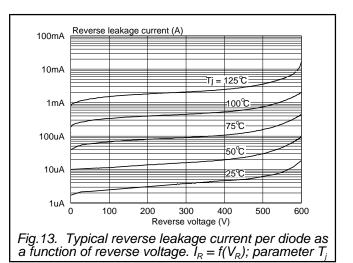


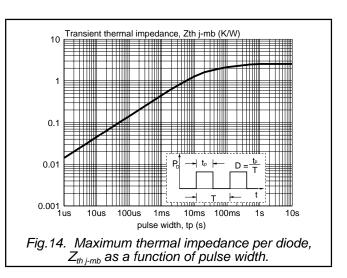








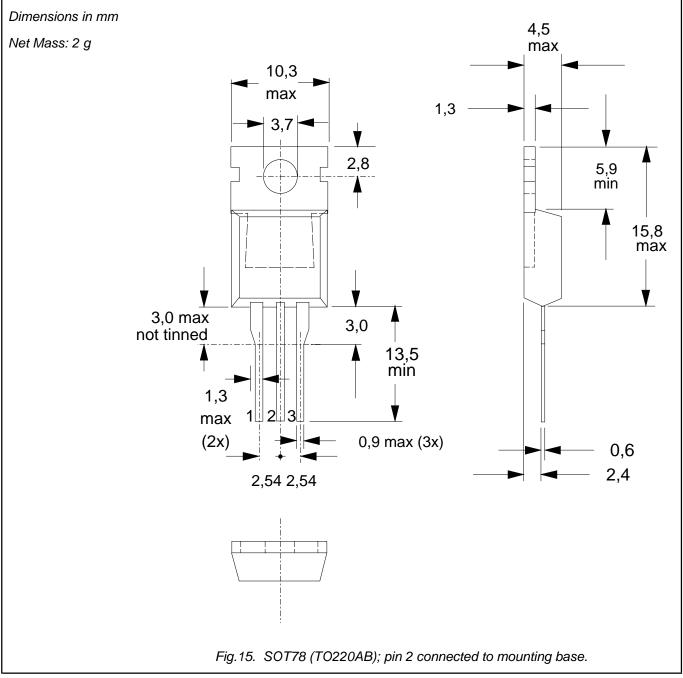




Product specification

BYC10-600CT

MECHANICAL DATA



Notes

Refer to mounting instructions for SOT78 (TO220) envelopes.
Epoxy meets UL94 V0 at 1/8".

BYC10-600CT

DEFINITIONS

Data sheet status		
Objective specification	This data sheet contains target or goal specifications for product development.	
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.	
Product specification	This data sheet contains final product specifications.	
Limiting values		
or more of the limiting val operation of the device at	in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one lues may cause permanent damage to the device. These are stress ratings only and t these or at any other conditions above those given in the Characteristics sections of applied. Exposure to limiting values for extended periods may affect device reliability.	
Application information		
Where application inform	ation is given, it is advisory and does not form part of the specification.	
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